

## PATENT ASSIGNMENT COVER SHEET

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<b>SUBMISSION TYPE:</b>	NEW ASSIGNMENT
<b>NATURE OF CONVEYANCE:</b>	ASSIGNMENT
<b>CONVEYING PARTY DATA</b>	
<b>Name</b>	<b>Execution Date</b>
HSING-CHIH LIU	05/16/2014
CHIA-HAO YANG	05/19/2014
YING-CHIH CHEN	05/16/2014
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<b>PROPERTY NUMBERS Total: 1</b>	
<b>Property Type</b>	<b>Number</b>
<b>Application Number:</b>	14271792
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<b>SIGNATURE:</b>	/Daniel R. McClure/
<b>DATE SIGNED:</b>	05/23/2014
<b>Total Attachments: 3</b>	
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## ASSIGNMENT

WHEREAS, Hsing-Chih LIU, Chia-Hao YANG and Ying-Chih CHEN hereafter referred to as ASSIGNOR, has/have invented certain new and useful improvements as described and set forth in the below identified application for United States Letters Patent:

Title: BONDING PAD ARRANGMENT DESIGN FOR MULTI-DIE SEMICONDUCTOR PACKAGE STRUCTURE

Filed: 14/271,792 Serial No. 2014-05-07

Executed on: \_\_\_\_\_

WHEREAS, MediaTek Inc. of No. 1, Dusing Rd. 1<sup>st</sup>, Science-Based Industrial Park, Hsin-Chu 300, Taiwan, R.O.C. hereinafter referred to as ASSIGNEE, is desirous of acquiring ASSIGNOR'S interest in the said invention and application and in any U.S. Letters Patent which may be granted on the same;

NOW, THEREFORE, TO ALL WHOM IT MAY CONCERN: Be it known that, for good and valuable consideration, receipt of which is hereby acknowledged by Assignor, Assignor has/have sold, assigned and transferred, and by these presents does/do sell, assign and transfer unto the said Assignee, and Assignee's successors and assigns, all his/her/their rights, title and interest in and to the said invention and application and all future improvements thereon, and in and to any Letters Patent which may hereafter be granted on the same in the United States, the said interest to be held and enjoyed by said Assignee as fully and exclusively as it would have been held and enjoyed by said Assignor had this Assignment and transfer not been made, to the full end and term of any Letters Patent which may be granted thereon, or of any division, renewal, continuation in whole or in part, substitution, conversion, reissue, prolongation or extension thereof.

Assignor further agrees/agree that he/she/they will, without charge to said Assignee, but at Assignee's expense, cooperate with Assignee in the prosecution of said application and/or applications, execute, verify, acknowledge and deliver all such further papers, including applications for Letters Patent and for the reissue thereof, and instruments of assignment and transfer thereof, and will perform such other acts as Assignee lawfully may request, to obtain or maintain Letters Patent for said invention and improvement, and to vest title thereto in said Assignee, or Assignee's successors and assigns.

IN TESTIMONY WHEREOF, Assignor has/have signed his/her/their name(s) on the date(s) indicated.

# ASSIGNMENT

Hsing chih Liu

Hsing-Chih LIU

2014.5.16

Date

Chia-Hao YANG

Date

Ying Chih Chen

Ying-Chih CHEN

2014.5.16

Date

# ASSIGNMENT

Hsing-Chih LIU

Date

Chia-Hao Yang  
Chia-Hao YANG

2014 or. 1P  
Date

Ying-Chih CHEN

Date